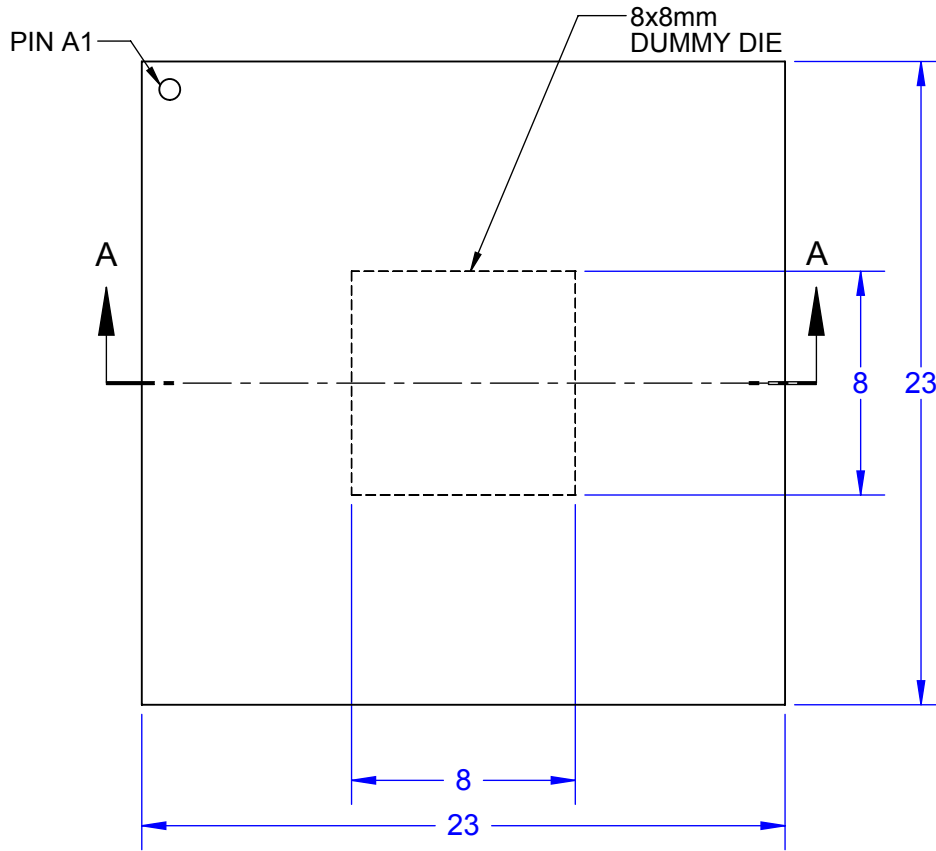
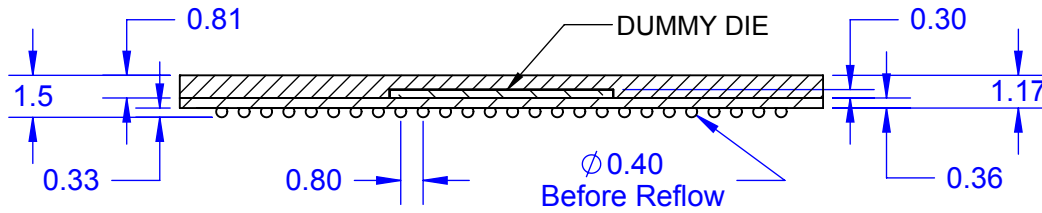
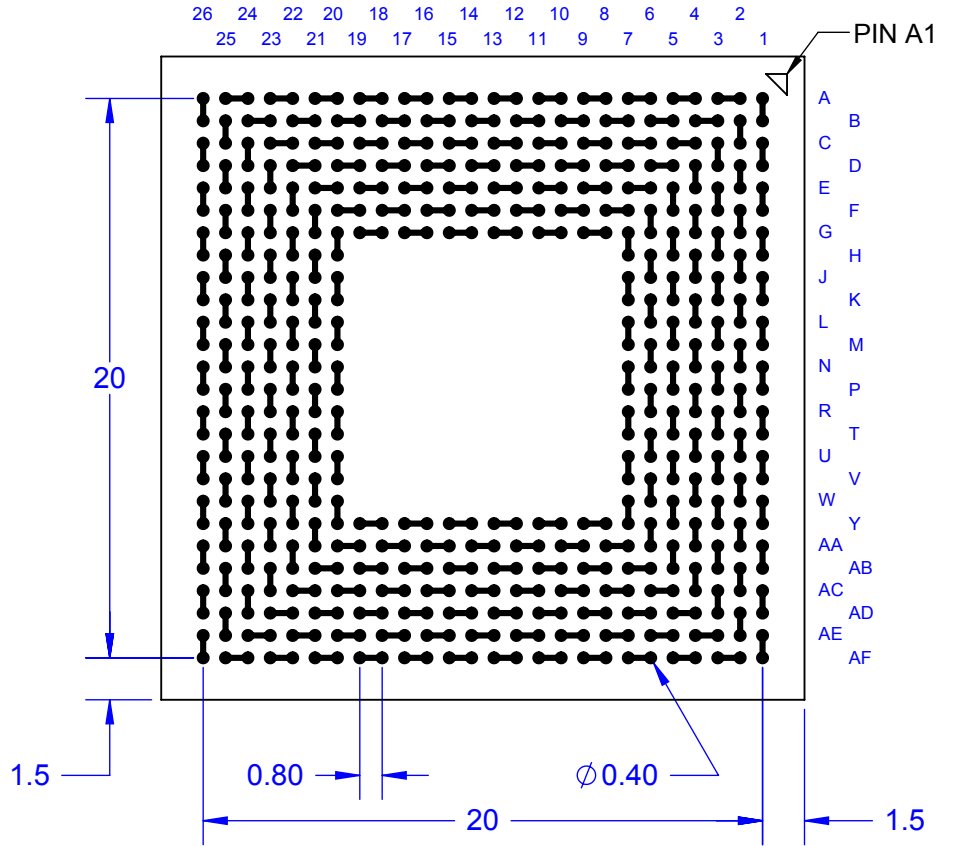


TOP VIEW



BALL VIEW



SECTION A-A

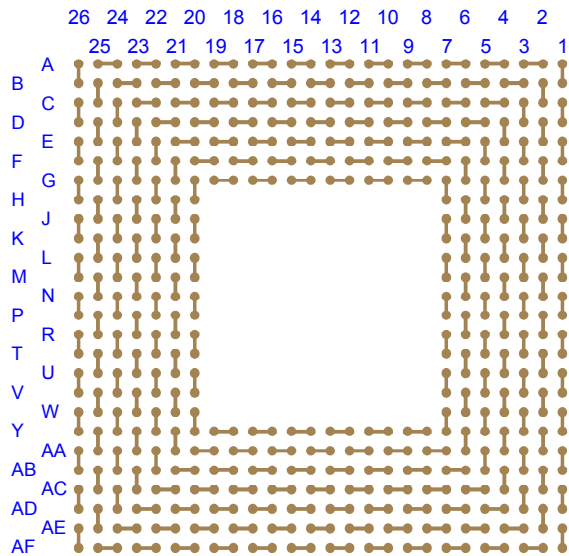
Notes: (Unless Otherwise Specified).

- 1) ALL DIMENSIONS ARE IN MM.
- 2) SOLDER BALL ALLOY: SEE PART NUMBER TABLE.
- 3) BALL DIAMETER (BEFORE REFLOW): 0.40mm.
- 4) SOLDER MASK DEFINED PAD OPENING: 0.33mm (13 MIL).
- 5) PAD Cu DIAMETER: 0.508mm (20 MIL).
- 6) SUBSTRATE MATERIAL: BT.
- 7) DUMMY DIE IS OPTIONAL.
- 8) DAISY CHAIN PATTERN (SEE PAGE 2).
- 9) MSL-3 RECOMMENDED BAKING 24 HOURS @ 125°C TO REMOVE MOISTURE PRIOR SOLDERING TO PC BOARD.

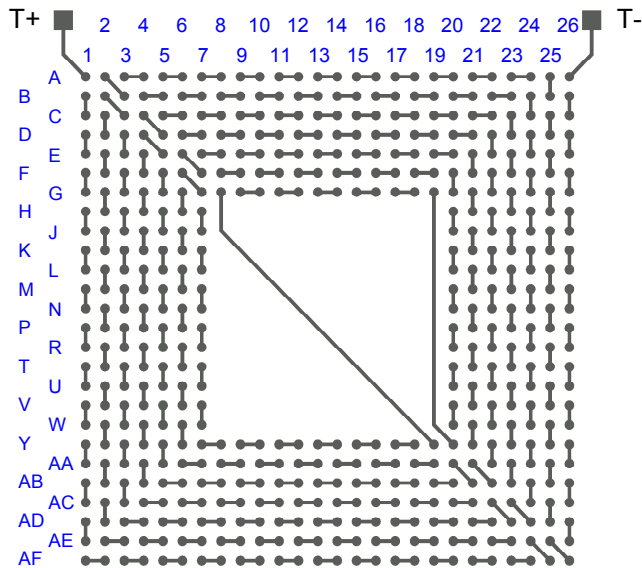
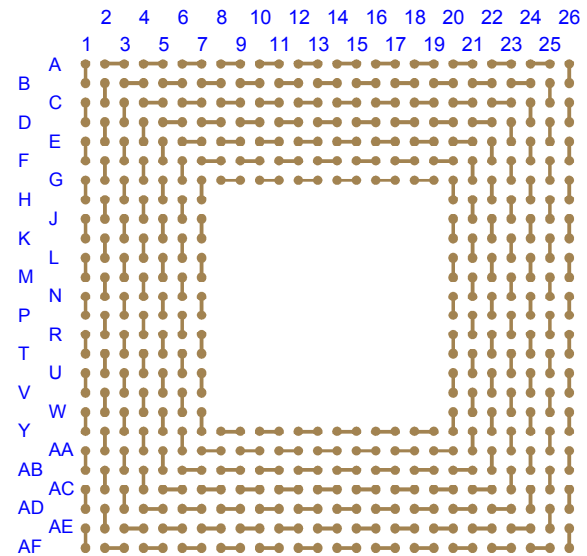
PART NUMBER TABLE				
PART NUMBER	BALL ALLOY	BALL CODE	RoHS	Si DIE
BGA532T.8C-DC266D	Sn96.5/Ag3.0/Cu0.5	SAC305	YES	YES
BGA532T.8-DC266D	Sn63/Pb37	Sn63	NO	YES

APPROVALS	DATE	TopLine®			
DRAWN T.Au	04/27/14				
ENG M. Hart	04/27/14	TITLE		BGA532T.8C-DC266D DAISY CHAIN DUMMY	
MFG		SCALE	SIZE	DRAWING NO.	REV
QA		3.7:1	A	582660	A
CUST		DO NOT SCALE DRAWING			SHEET 1 OF 2
REVISED					

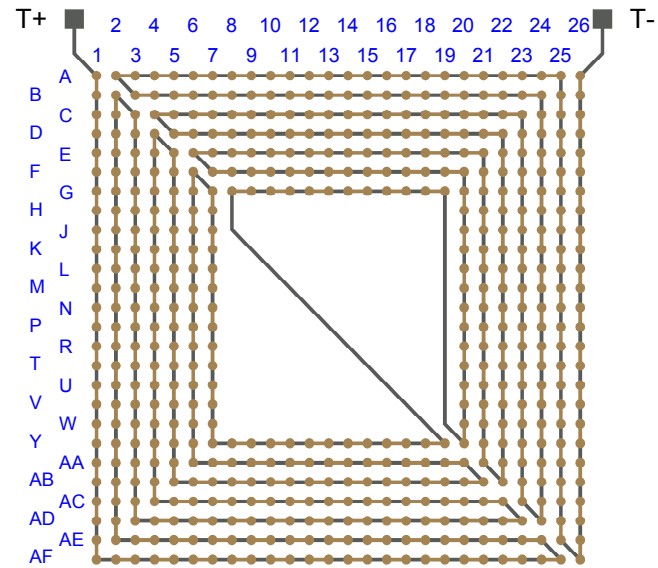
BALL VIEW



BOTTOM SIDE (TOP X-RAY VIEW)



TEST VEHICLE BOARD



AFTER MOUNTING

Notes:

- 1) PCB BOARD DIMENSIONS ARE PRESENTED ONLY AS A GUIDELINE. DESIGNERS SHOULD USE THEIR OWN EXPERIENCE WHEN DESIGNING PCB.
- 2) PCB Cu BALL PAD DIAMETER 0.508mm (20 MIL).
- 3) PCB DAISY CHAIN TRACING LINE WIDTH 0.152mm (6 MIL).
- 4) SMD (SOLDER MASK DEFINED) PAD OPENING: 0.33mm (13 MIL).

TopLine®			
TITLE		BGA532T.8-DC266D DAISY CHAIN DUMMY	
SCALE	SIZE	DRAWING NO.	REV
3:1	A	582660	A
DO NOT SCALE DRAWING			SHEET 2 OF 2